

Abstract of the Disclosure

A thin, lightweight retention mechanism with a spring force holds an integrated circuit package to a circuit board. The retention mechanism consists of a pressure plate, a backing plate, and a fastening means for applying a deforming
5 force to the plates, such as screws and nuts. The plates are paraboloid or dish-shaped and made of an elastically deformable material, such as steel. The fastening means simultaneously applies deforming forces to the peripheries of the plates to create a continuous spring force to effect electrical continuity between the integrated circuit package and the circuit board. In addition, a method of testing the retention
10 mechanism and a method of assembling the retention mechanism are disclosed.

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